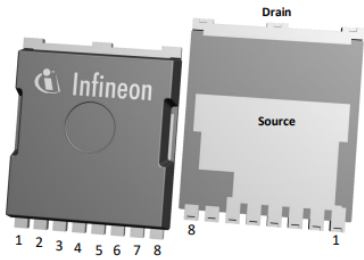


英飞凌CoolGaN™ G5

英飞凌CoolGaN™晶体管 650 V G5

英飞凌的 CoolGaN™是一款高效氮化镓 (GaN) 晶体管，专为 650 V 的功率转换而设计。它可实现更高的功率密度，降低系统 BOM 成本，并有助于实现小型化外形尺寸。它采用 200 毫米（8 英寸）晶圆技术和全自动生产线生产，具有生产公差小的特点，最高的产品质量。这使其适用于从消费电子到工业的广泛应用。

TOLL



特性

- 增强型晶体管
- 超快速开关
- 无反向恢复电荷
- 能够反向传导
- 低栅极和输出电荷
- 出色的换向耐用性
- 2kV HBM ESD 标准

优点

- 常闭晶体管技术确保安全运行
- 实现快速、精确的电力输送控制
- 提高系统效率和可靠性
- 确保在严苛条件下的稳健表现

这些共性使 CoolGaN™成为电源转换领域的游戏规则颠覆者，提供了一个令人叹服的高效、紧凑和可靠的完美组合。

潜在的应用

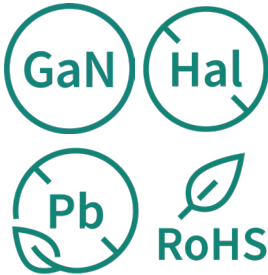
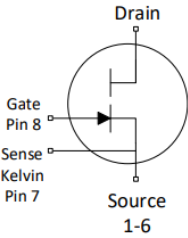
基于半桥硬开关和软开关拓扑（例如图腾柱 PFC 和高频 LLC）的工业、通信、数据中心 SMPS，以及充电器和适配器。

产品认证

完全符合 JEDEC 工业应用标准

表1 主要性能参数

Parameter	Value	Unit
$V_{DS,max}$	650	V
$V_{DS,trans-max}$	900	V
$R_{DS(on),max}$	30	mΩ
$Q_{g,typ}$	11	nC
$I_{D,pulse}$	120	A
$Q_{oss} @ 400 V$	82	nC
Q_{rr}	0	nC



Type / Ordering code	Package	Marking	Related links
IGT65R025D2	PG-HSOF-8	65R025D2	see Appendix A

本数据手册的原文使用英文撰写。为方便起见，英飞凌提供了译文；由于翻译过程中可能使用了自动化工具，英飞凌不保证译文的准确性。为确认准确性，请务必访问 infineon.com 参考最新的英文版本（控制文档）。



目录

说明..... 1

最大额定值 3

热特性..... 5

电气特性 6

电气特性图..... 8

测试电路 13

封装外形 14

附录 A 17

修订记录 18

商标..... 18

免责声明..... 18

1 最大额定值

除非另有说明，否则 $T_j = 25^\circ\text{C}$ 。超过最大额定值的应力可能会对器件造成永久性损坏。为获得最佳使用寿命和可靠性，英飞凌建议工作条件不要持续超过所述最大额定值的 80%（除非另有明确说明）。如需更多信息，请联系您当地的英飞凌销售办事处。

表 2 最大额定值

Parameter	Symbol	Values			Unit	Note / Test condition
		Min.	Typ.	Max.		
Drain source voltage, continuous	$V_{DS,max}$	-	-	650	V	$V_{GS} = 0\text{ V}$, derating recommendation according JEDEC JEP198
Leakage current at drain source transient voltage	$I_{DS,trans}$	-	-	28	mA	$V_{GS} = 0\text{ V}$, $V_{DS,trans} = 900\text{ V}$
Drain source voltage transient	$V_{DS,trans}$	-	-	900	V	<1% duty cycle, <1 μs , 1 million pulses
Drain source voltage, pulsed	$V_{DS,pulsed}$	-	-	750 650	V	$T_j = 25^\circ\text{C}$; $V_{GS} \leq 0\text{ V}$; cumulated stress time $\leq 1\text{ h}$ $T_j = 125^\circ\text{C}$; $V_{GS} \leq 0\text{ V}$; cumulated stress time $\leq 1\text{ h}$
Switching surge voltage, pulsed	$V_{DS,surge}$	-	-	750	V	DC bus voltage = 700 V; turn off $V_{DS,pulse} = 750\text{ V}$; turn on $I_{D,pulse} = 63\text{ A}$; $T_j = 105^\circ\text{C}$; $f \leq 100\text{ kHz}$, $t \leq 100\text{ s}$ (10 million pulses)
Continuous current, drain source ¹⁾	I_D	-	-	70	A	$T_C = 25^\circ\text{C}$; $T_j = T_{j,max}$
Pulsed current, drain source	$I_{D,pulse}$	-120 -84	-	120 84	A	$T_j = 25^\circ\text{C}$; $I_G = 60\text{ mA}$; See Diagram 3, 5 $T_j = 125^\circ\text{C}$; $I_G = 60\text{ mA}$; See Diagram 4, 6
Gate current, continuous ²⁾	$I_{G,avg}$	-	-	46	mA	$T_j = -55^\circ\text{C}$ to $T_j = 150^\circ\text{C}$; See Table 9
Gate current, pulsed ²⁾	$I_{G,pulsed}$	-4.6	-	4.6	A	$T_j = -55^\circ\text{C}$ to $T_j = 150^\circ\text{C}$; $t_{pulse} = 50\text{ ns}$, $f = 100\text{ kHz}$; See Table 9
Gate source voltage, continuous ²⁾	V_{GS}	-10	-	-	V	$T_j = -55^\circ\text{C}$ to $T_j = 150^\circ\text{C}$; See Diagram 12
Gate source voltage, pulsed ²⁾	$V_{GS,pulse}$	-25	-	-	V	$T_j = -55^\circ\text{C}$ to $T_j = 150^\circ\text{C}$; $t_{pulse} = 50\text{ ns}$, $f = 100\text{ kHz}$; open drain
Power dissipation	P_{tot}	-	-	236	W	$T_C = 25^\circ\text{C}$
Operating junction temperature	T_j	-55	-	150	$^\circ\text{C}$	-
Storage temperature	T_{stg}	-55	-	150	$^\circ\text{C}$	Max shelf life depends on storage conditions
Drain-source voltage slew-rate	dv/dt	-	-	200	V/ns	-

¹⁾受 $T_{j,max}$ 限制。最大占空比 $D = 0.75$

² 我们建议使用先进的驱动技术来优化器件性能。请参阅栅极驱动器应用说明了解更多详细内容。



2 热特性

表3 热特性

Parameter	Symbol	Values			Unit	Note / Test condition
		Min.	Typ.	Max.		
Thermal resistance, junction - case	R_{thJC}	-	-	0.53	°C/W	-
Thermal resistance, junction - ambient	R_{thJA}	-	-	86	°C/W	Device on PCB, minimum footprint
Thermal resistance, junction - ambient for SMD version	R_{thJA}	-	-	62	°C/W	Device on 40 mm*40 mm*1.5 mm epoxy PCB FR4 with 6 cm ² (one layer, 70 μm thickness) copper area for tab (source) connection and cooling. PCB is vertical without air stream cooling.
Reflow soldering temperature	T_{sold}	-	-	260	°C	MSL1

3 电气特性

除非另有规定, $T_j = 25^\circ\text{C}$

表4 静态特性

Parameter	Symbol	Values			Unit	Note / Test condition
		Min.	Typ.	Max.		
Gate threshold voltage	$V_{GS(th)}$	0.9 -	1.2 1	1.6 -	V	$I_{DS}=6.1\text{ mA}$; $V_{DS}=10\text{ V}$; $T_j=25^\circ\text{C}$ $I_{DS}=6.1\text{ mA}$; $V_{DS}=10\text{ V}$; $T_j=150^\circ\text{C}$
Gate-Source reverse clamping voltage	$V_{GS, clamp}$	-	-	-8	V	$I_{GS}=-1\text{ mA}$
Drain-Source leakage current	I_{DSS}	-	2.3 46	230 -	μA	$V_{DS}=650\text{ V}$, $V_{GS}=0\text{ V}$, $T_j=25^\circ\text{C}$ $V_{DS}=650\text{ V}$, $V_{GS}=0\text{ V}$, $T_j=150^\circ\text{C}$
Drain-Source on-state resistance	$R_{DS(on)}$	-	0.025 0.053	0.030 -	Ω	$I_G=60\text{ mA}$; $I_D=18\text{ A}$; $T_j=25^\circ\text{C}$ $I_G=60\text{ mA}$; $I_D=18\text{ A}$; $T_j=150^\circ\text{C}$
Gate resistance	$R_{G,int}$	-	0.7	-	Ω	LCR impedance measurement; $f=f_{res}$, open drain;

表 5 动态特性

Parameter	Symbol	Values			Unit	Note / Test condition
		Min.	Typ.	Max.		
Input capacitance	C_{iss}	-	780	-	pF	$V_{GS}=0\text{ V}$; $V_{DS}=400\text{ V}$, $f=1\text{ MHz}$
Output capacitance	C_{oss}	-	130	-	pF	$V_{GS}=0\text{ V}$, $V_{DS}=400\text{ V}$, $f=1\text{ MHz}$
Reverse transfer capacitance	C_{rss}	-	1.8	-	pF	
Effective output capacitance, energy related ³⁾	$C_{o(er)}$	-	150	-	pF	$V_{DS}=0\text{ to }400\text{ V}$
Effective output capacitance, time related ⁴⁾	$C_{o(tr)}$	-	204	-	pF	$V_{GS}=0\text{ V}$; $V_{DS}=0\text{ to }400\text{ V}$; $I_D=\text{const}$
Output charge	Q_{oss}	-	82	-	nC	$V_{DS}=0\text{ to }400\text{ V}$
Coss stored energy	E_{oss}	-	12	-	μJ	
Turn-on delay time	$t_{d(on)}$	-	11	-	ns	$I_D=18\text{ A}$; $R_{ON}=2.2\text{ Ohm}$; $R_{OFF}=2.2\text{ Ohm}$; $R_{SS}=150\text{ Ohm}$; $C_C=6.8\text{ nF}$; $V_{DRV}=12\text{ V}$; see Table 8
Turn-off delay time	$t_{d(off)}$	-	18	-	ns	
Rise time	t_r	-	12	-	ns	
Fall time	t_f	-	9	-	ns	

3) $C_{o(er)}$ 是固定电容, 当 V_{DS} 从 0 升至 400 V 时, 其存储能量与 C_{oss} 相同

4) $C_{o(tr)}$ 是一个固定电容, 当 V_{DS} 从 0 升至 400 V 时, 其充电时间与 C_{oss} 相同

表6 栅极电荷特性

Parameter	Symbol	Values			Unit	Note / Test condition
		Min.	Typ.	Max.		
Gate charge	Q_G	-	11	-	nC	$V_{GS}=0\text{ to }3\text{ V}$; $V_{DS}=400\text{ V}$, $I_D=18\text{ A}$

表7 反向传导特性

Parameter	Symbol	Values			Unit	Note / Test condition
		Min.	Typ.	Max.		
Source-Drain reverse voltage	V_{SD}	-	2.0	2.4	V	$V_{GS}=0\text{ V}; I_{SD}=18\text{ A}$
Pulsed current, reverse	$I_{SD,pulse}$	-	-	120	A	$I_G=60\text{ mA}$
Reverse recovery charge ⁵⁾	Q_{rr}	-	0	-	nC	$I_{SD}=18\text{ A}; V_{DS}=400\text{ V}$

⁵⁾ 不包括 Q_{oss}

4 电气特性图

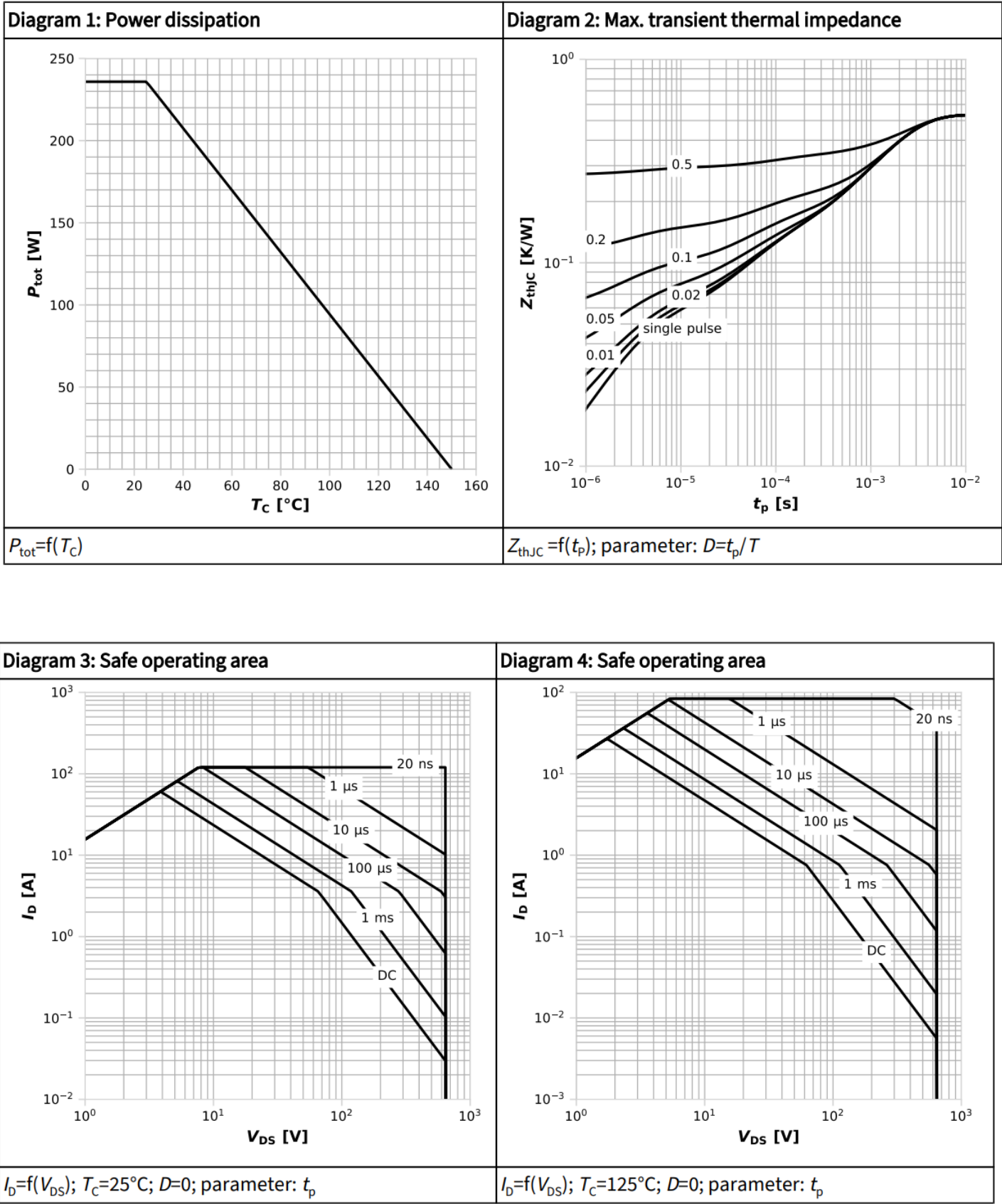
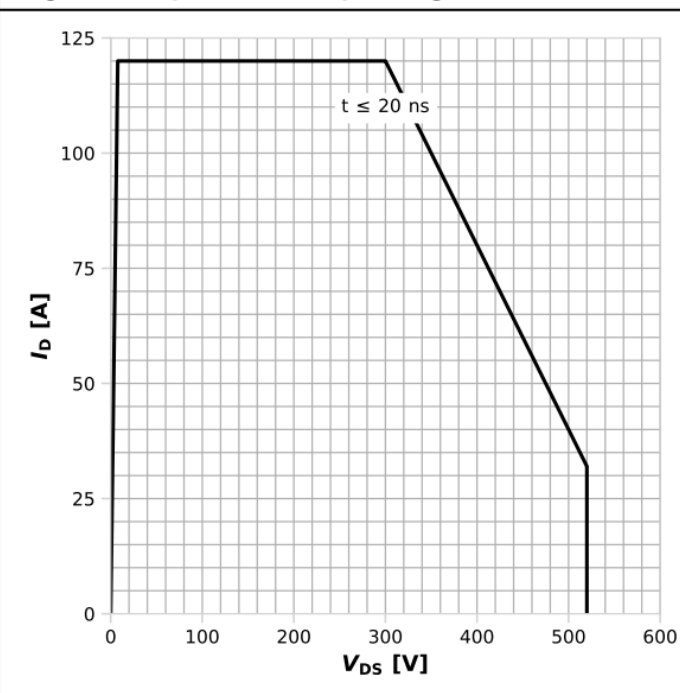


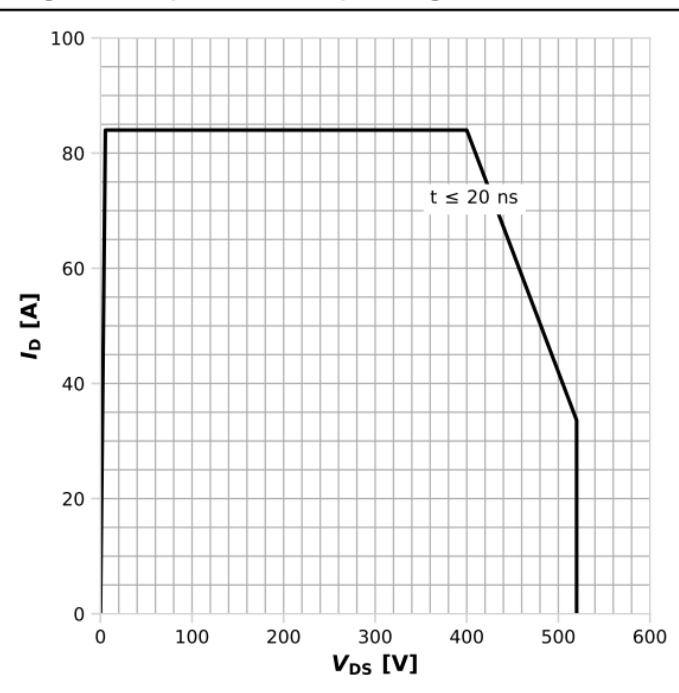


Diagram 5: Repetitive safe operating area



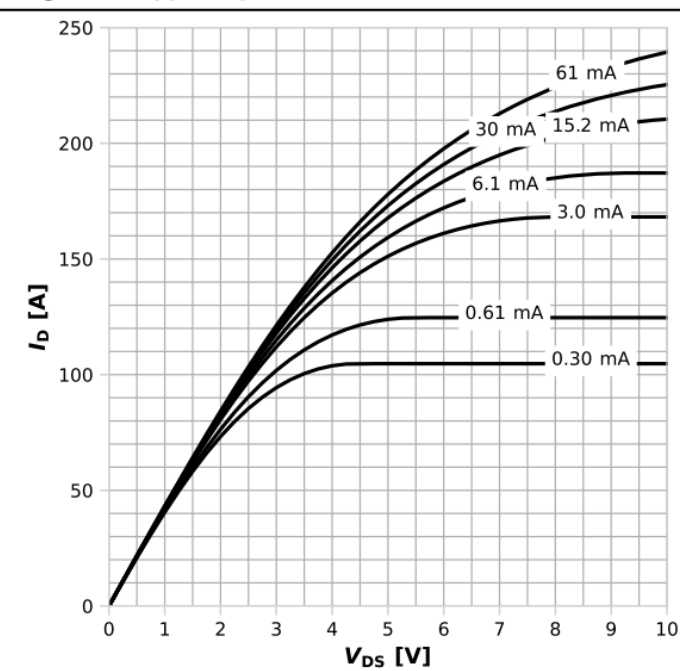
$I_D=f(V_{DS})$; $T_C=25^{\circ}\text{C}$; $T_J\leq 150^{\circ}\text{C}$; parameter: t_p

Diagram 6: Repetitive safe operating area



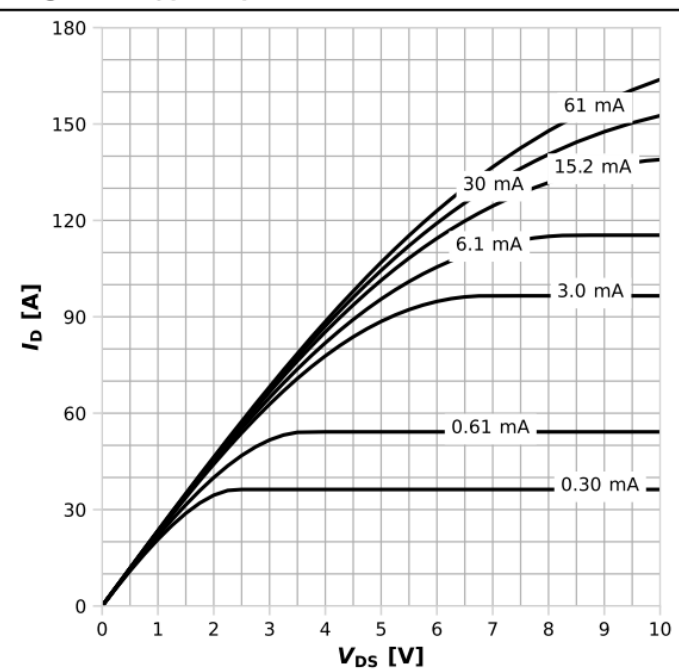
$I_D=f(V_{DS})$; $T_C=125^{\circ}\text{C}$; $T_J\leq 150^{\circ}\text{C}$; parameter: t_p

Diagram 7: Typ. output characteristics



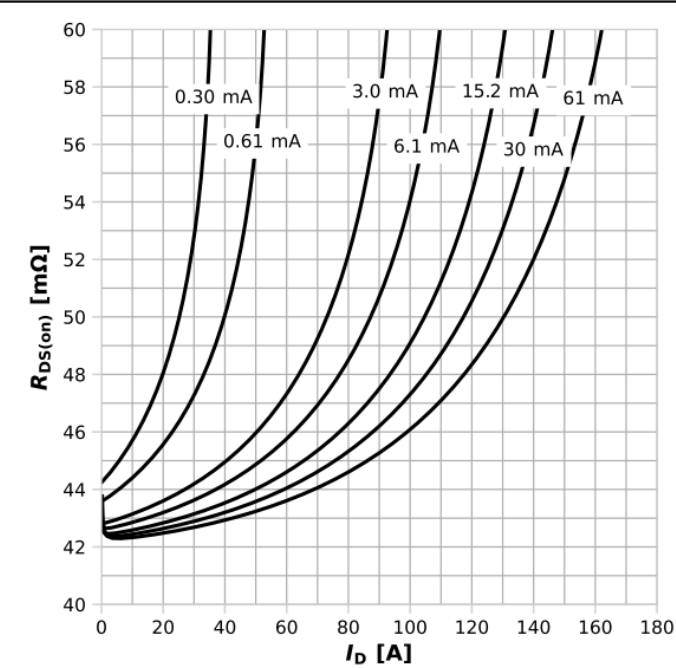
$I_D=f(V_{DS})$; $T_J=25^{\circ}\text{C}$; parameter: I_{GS}

Diagram 8: Typ. output characteristics



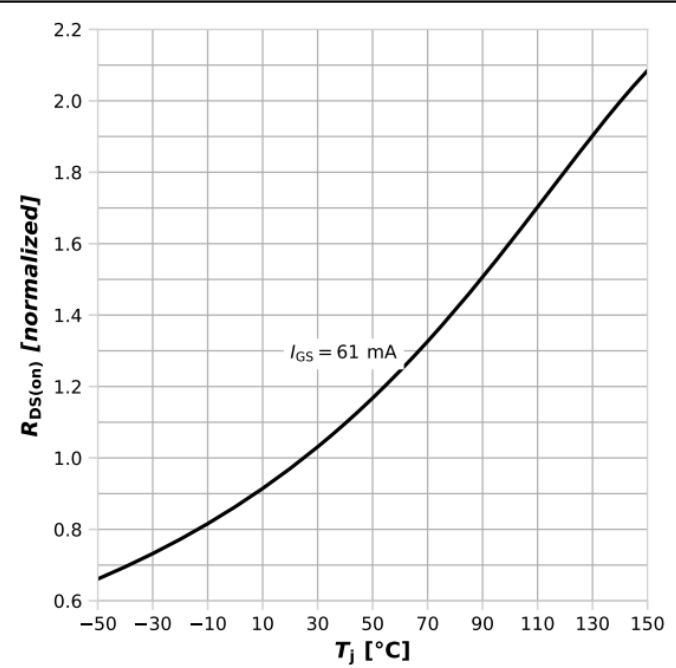
$I_D=f(V_{DS})$; $T_J=125^{\circ}\text{C}$; parameter: I_{GS}

Diagram 9: Typ. Drain-source on-state resistance



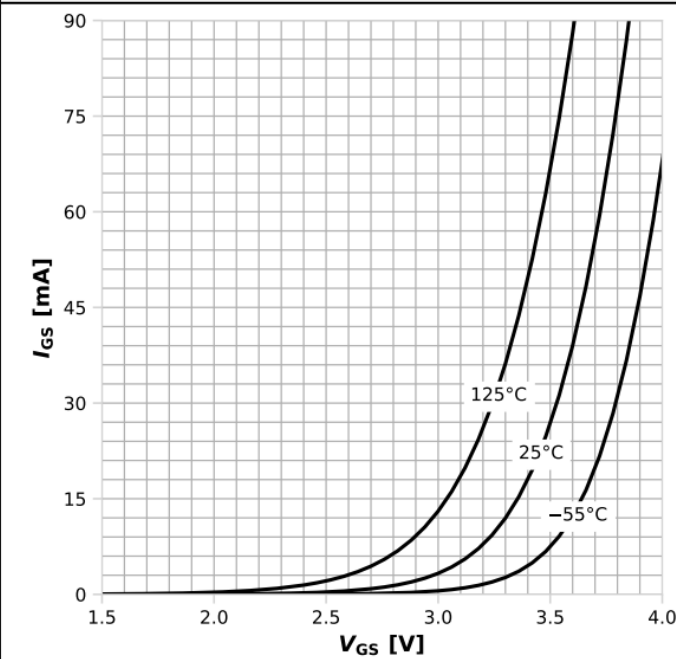
$R_{DS(on)} = f(I_D); T_j = 125^\circ\text{C}; \text{parameter: } I_{GS}$

Diagram 10: Drain-source on-state resistance



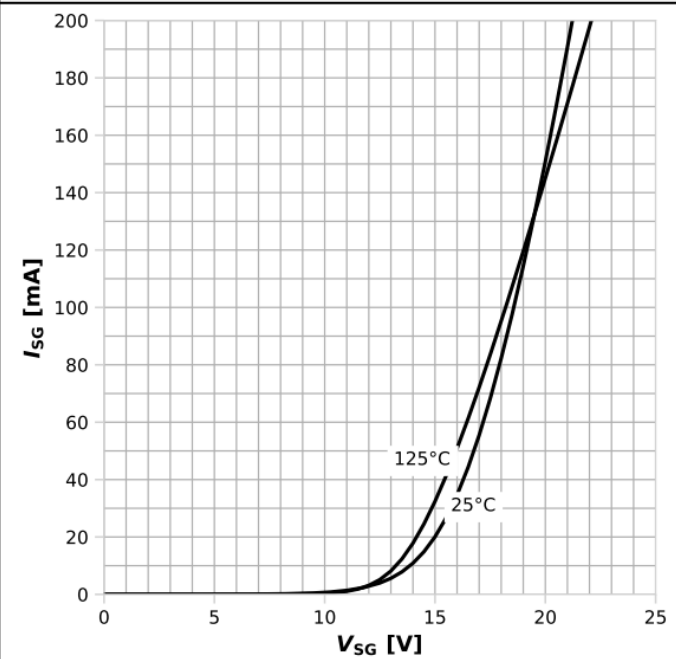
$R_{DS(on)} = f(T_j); I_D = 18 \text{ A}$

Diagram 11: Typ. gate characteristics forward



$I_{GS} = f(V_{GS}); \text{open drain}; \text{parameter: } T_j$

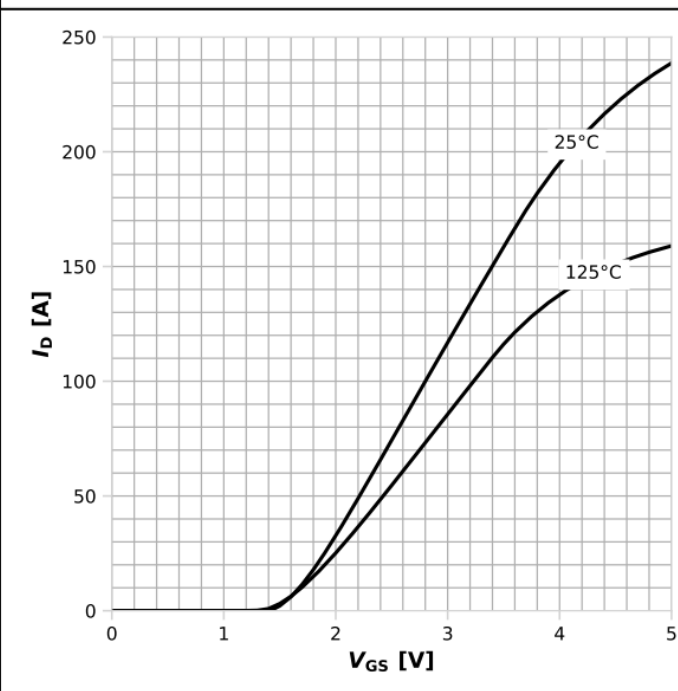
Diagram 12: Typ. gate characteristics reverse



$I_{SG} = f(V_{SG}); \text{parameter: } T_j$

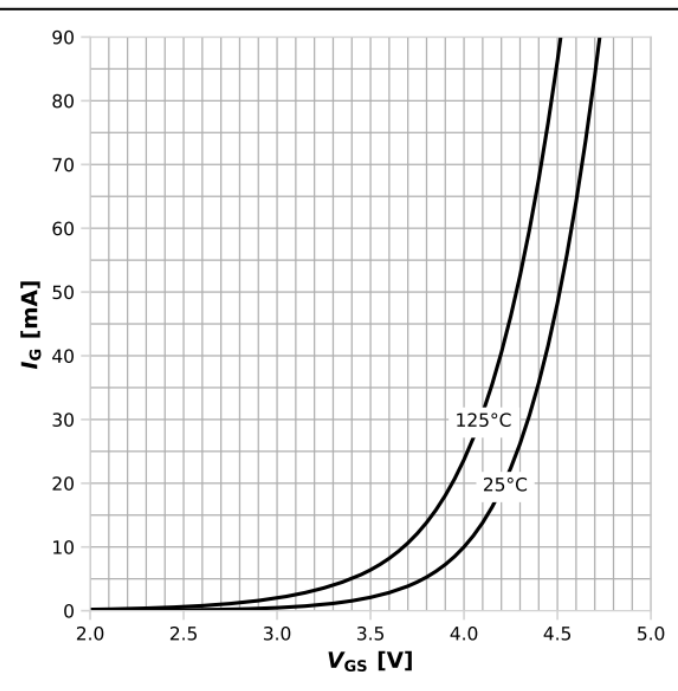


Diagram 13: Typ. transfer characteristics



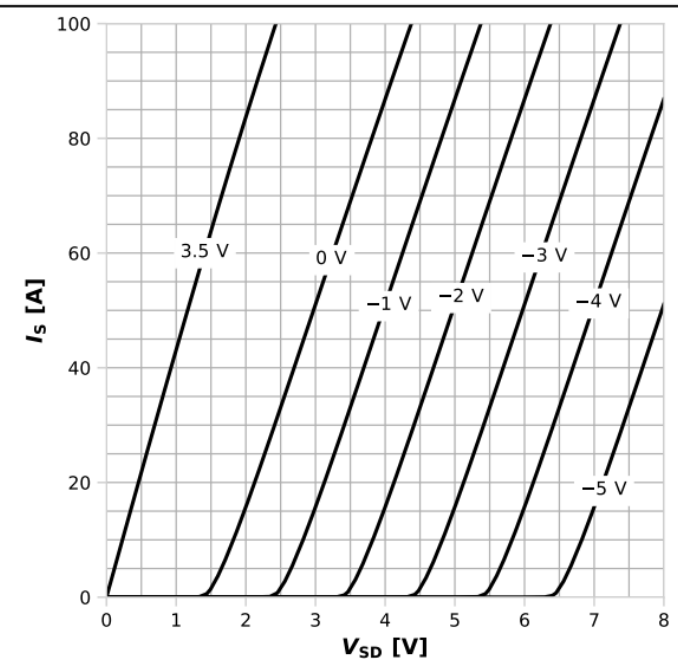
$I_D = f(I_{GS}); V_{DS} = 8V; \text{parameter: } T_j$

Diagram 14: Typ. transfer gate current characteristic



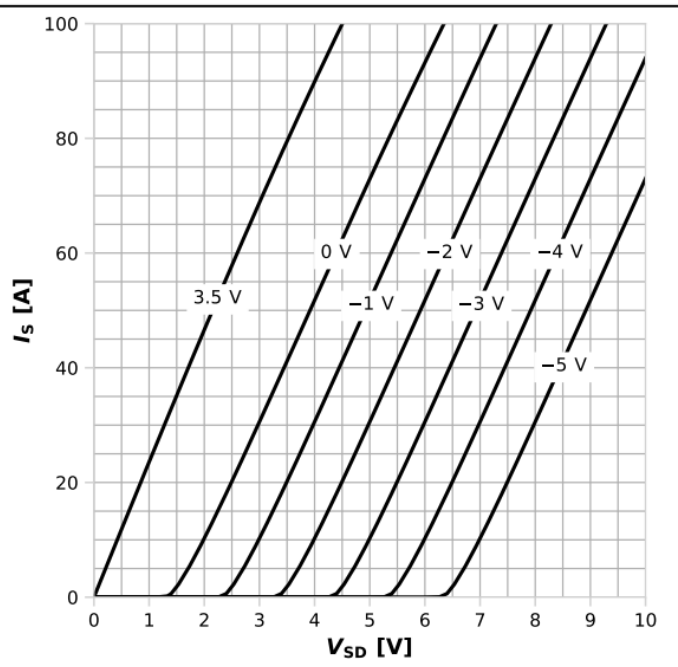
$I_G = f(V_{GS}); V_{DS} = 8V; \text{parameter: } T_j$

Diagram 15: Typ. channel reverse characteristics



$I_S = f(V_{SD}); T_j = 25^\circ\text{C}; \text{parameter: } V_{GS}$

Diagram 16: Typ. channel reverse characteristics



$I_S = f(V_{SD}); T_j = 125^\circ\text{C}; \text{parameter: } V_{GS}$

Diagram 17 Typ. gate charge

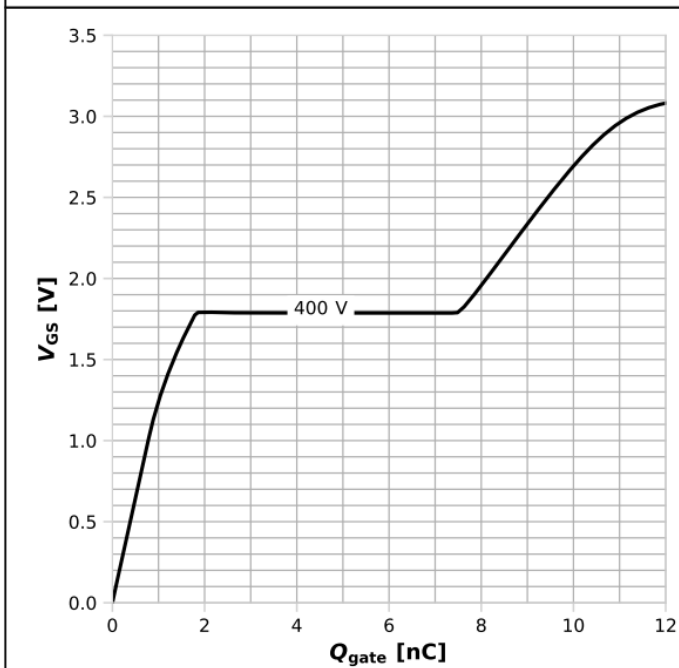

 $V_{GS}=f(Q_{gate}); I_D=18\text{ A pulsed}; I_G=4.5\text{ mA}; \text{parameter: } V_{DD}$

Diagram 18: Typ. capacitances

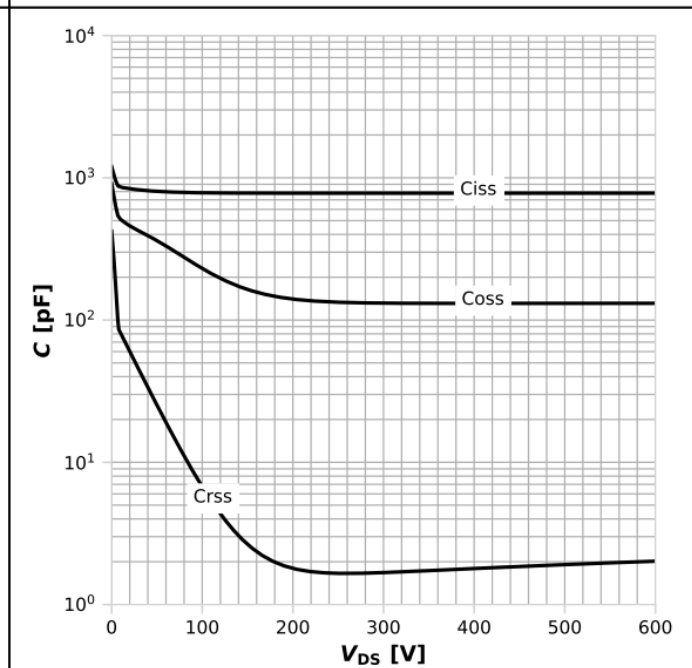

 $C=f(V_{DS}); V_{GS}=0\text{ V}$

Diagram 19: Typ. output charge

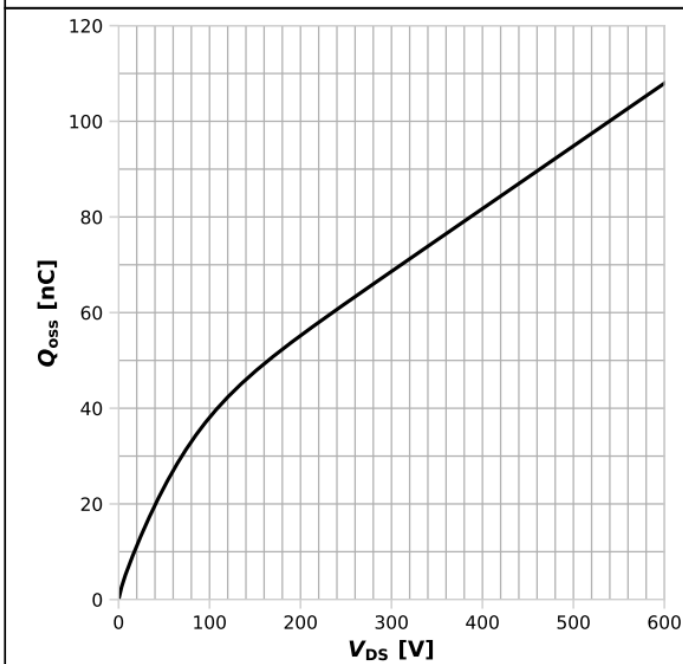
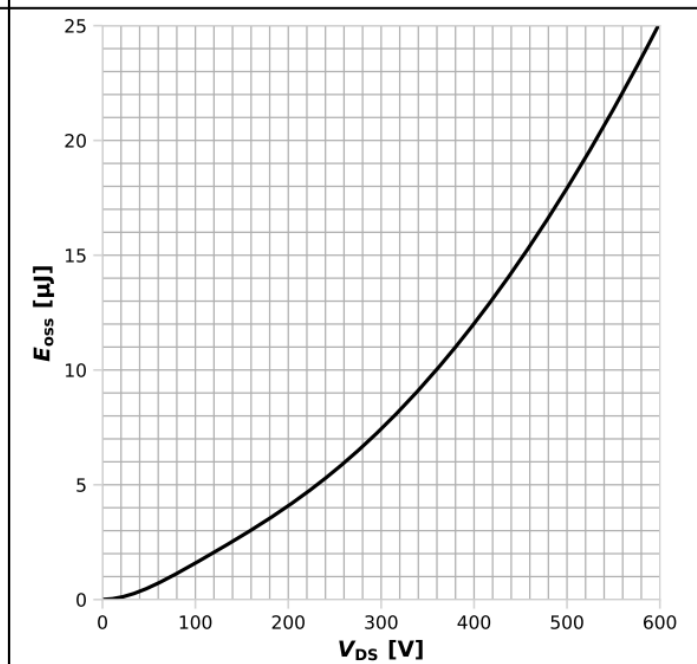

 $Q_{oss}=f(V_{DS})$

Diagram 20: Typ. Coss stored energy


 $E_{oss}=f(V_{DS})$

5 测试电路

表8 反向通道特性测试

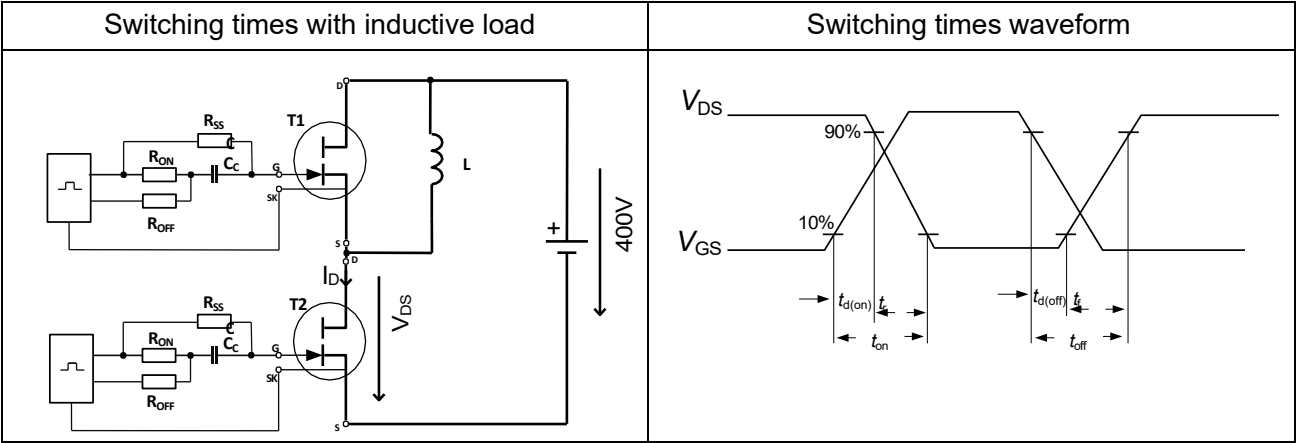
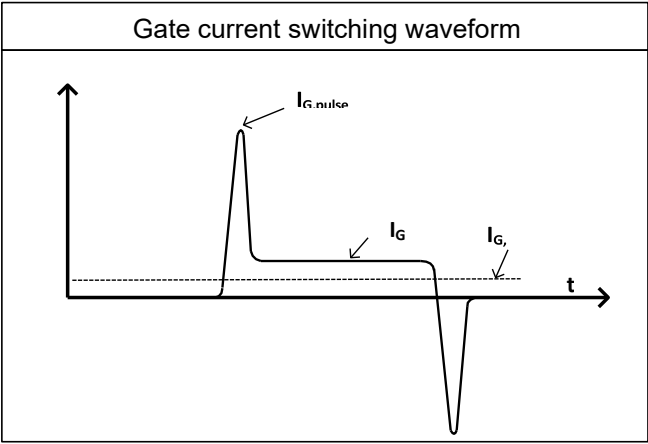
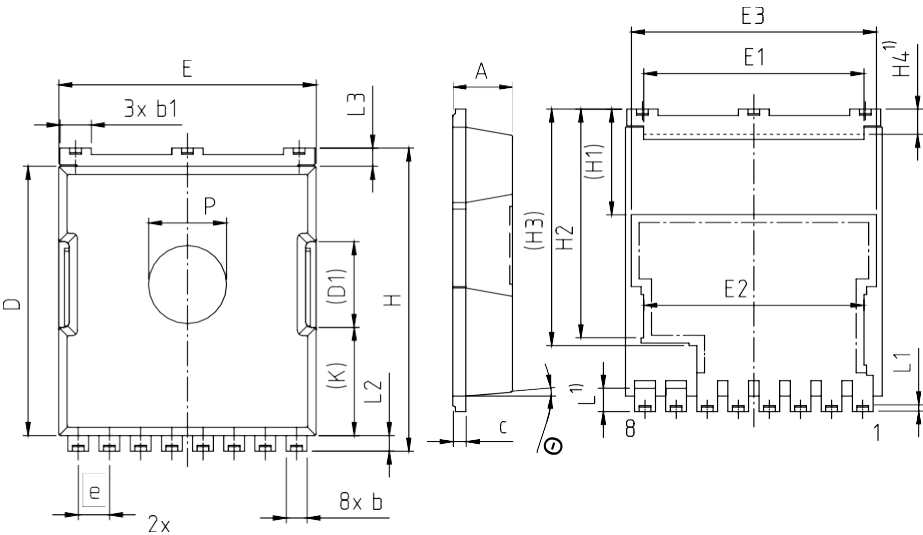


表9 栅极电流开关波形



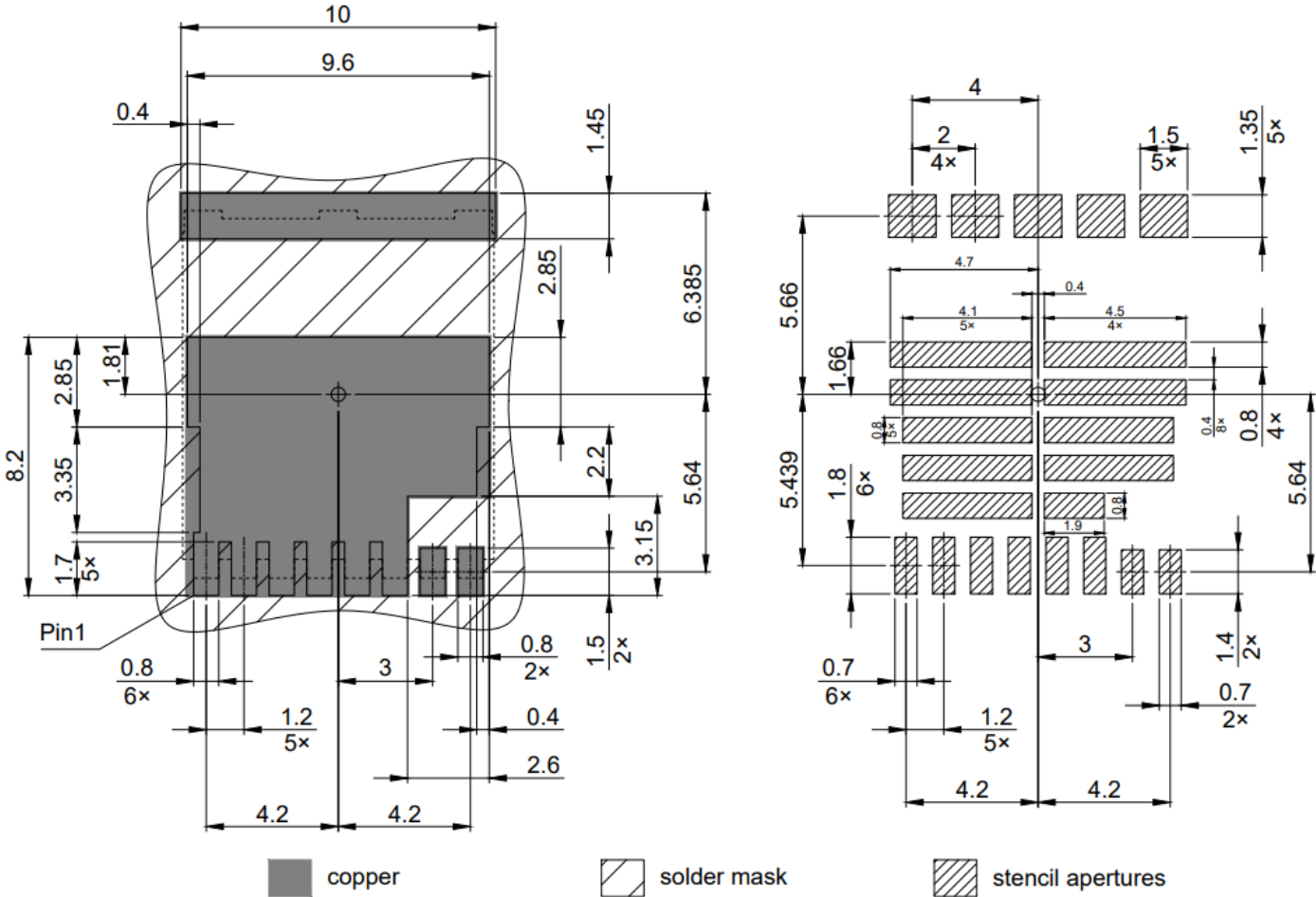
6 封装外形



PACKAGE - GROUP PG-HSOF-8-U04		
NUMBER:		
DIMENSIONS	MILLIMETERS	
	MIN.	MAX.
A	2.20	2.40
b	0.70	0.90
b1	1.10	1.30
c	0.40	0.60
D	10.275	10.575
D1	(3.20)	(3.40)
E	9.70	10.10
E1	8.40	8.60
E2	8.40	8.60
E3	9.36	9.56
e	1.20	
H	11.475	11.875
H1	(3.98)	(4.18)
H2	8.73	8.93
H3	(9.03)	(9.23)
H4	0.88	1.08
N	8	
K	(4.07)	(4.27)
L	0.80	1.00
L1	0.13	0.33
L2	0.50	0.70
L3	0.60	0.80
P	2.90	3.10
Θ	3.5°	6.5°

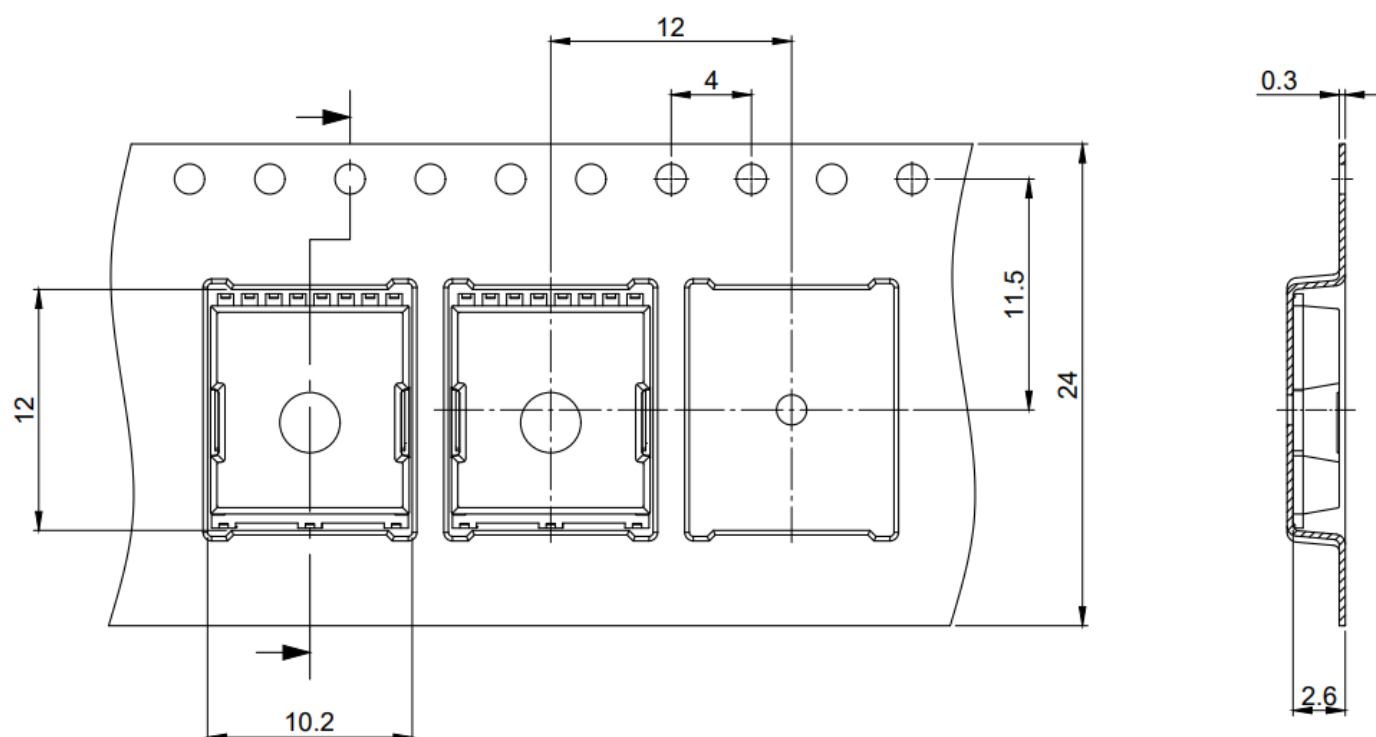
NOTES:
1) LEAD LENGTH UP TO ANTI FLASH PROFILE MOLD FLASHES EXCLUDED

图 1 PG-HSOF-8 外形图，尺寸单位为毫米



Based on stencil thickness 0.130 mm
All dimensions are in units mm

图 2 PG-HSOF-8 封装图，尺寸单位为毫米



All dimensions are in units mm

The drawing is in compliance with ISO 128-30, Projection Method 1 []

图 3 PG-HSOF-8 包装型号，尺寸单位为毫米

7 附录A

表 10 相关链接

- [CoolGaN™ GaN 650 V 网页](#)
- [CoolGaN™ GaN 650 V 可靠性白皮书](#)
- [CoolGaN™ GaN 650 V 栅极驱动器应用手册](#)
- [CoolGaN™ GaN 650 V 应用信息](#)

修订记录

IGT65R025D2

Revision 2024 - 11 - 28 , Rev. 1 . 0

历史修订记录

Revision	Date	Subjects (major changes since last revision)
1.0	2024-11-28	Release of final

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Edition 2025-04-21

Published by

Infineon Technologies AG

81726 Munich, Germany

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